

1.0A SURFACE MOUNT GLASS PASSIVATED RECTIFIER
Features

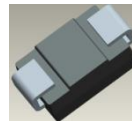
- Glass Passivated Die Construction for High Reliability
- Surge Overload Rating to 30A Peak
- Ideally Suited for Automated Assembly
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: SMA/SMB
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead-Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 ②③
- Polarity: Cathode Band or Cathode Notch
- Weight: SMA - 0.064 grams (Approximate)
SMB - 0.093 grams (Approximate)



Top View



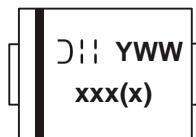
Bottom View

Ordering Information(Note 4)

Part Number	Qualification	Case	Packaging
S1x-13-F	Commercial	SMA	5,000/Tape & Reel
S1xB-13-F	Commercial	SMB	3,000/Tape & Reel

* x = Device type, e.g. S1A-13-F (SMA package); S1AB-13-F (SMB package).

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information


- XXX = Product Type Marking Code, ex: S1A (SMA Package)
- XXXX = Product Type Marking Code, ex: S1AB (SMB Package)
- ⌋|| = Manufacturers' Code Marking
- YWW = Date Code Marking
- Y = Last Digit of Year (ex: 4 for 2014)
- WW = Week Code (01 to 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	S1 A/AB	S1 B/BB	S1 D/DB	S1 G/GB	S1 J/JB	S1 K/KB	S1 M/MB	Unit
Peak Repetitive Reverse Voltage	V _{RRM}								
Working Peak Reverse Voltage	V _{RWM}	50	100	200	400	600	800	1000	V
DC Blocking Voltage	V _R								
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Rectified Output Current @ T _T = +100°C	I _O	1.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	30							A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal (Note 5)	R _{θJT}	30	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit
Forward Voltage @ I _F = 1.0A	V _{FM}	—	—	1.1	V
Peak Reverse Leakage Current @ T _A = +25°C at Rated DC Blocking Voltage @ T _A = +125°C	I _{RM}	—	—	5.0 100	μA
Reverse Recovery Time (Note 6)	t _{rr}	—	1.8	3.0	μs
Typical Total Capacitance (Note 7)	C _T	—	10	—	pF

- Notes: 5. Thermal resistance junction to terminal, unit mounted on PC board with 5.0 mm² (0.013 mm thick) copper pads as heat sink.
6. Measured with I_F = 0.5A, I_R = 1.0A, I_{RR} = 0.25A.
7. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

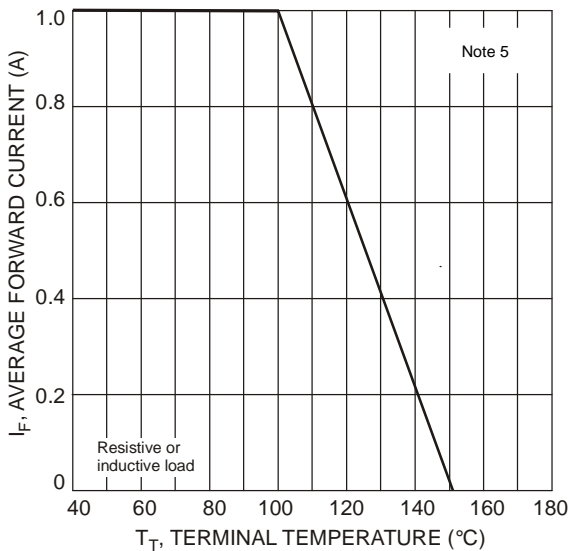


Fig. 1 Forward Current Derating Curve

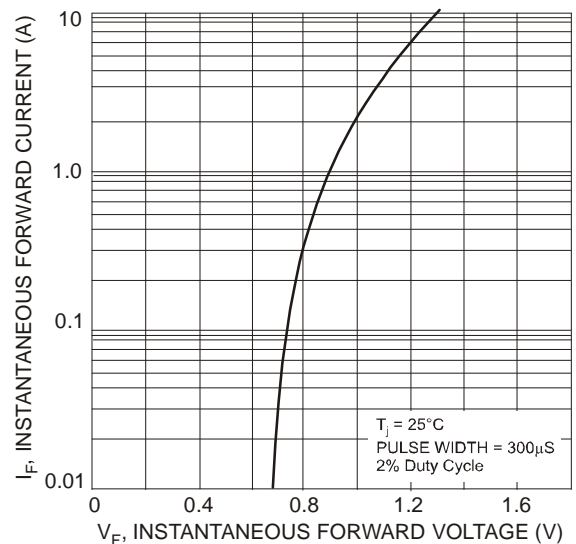


Fig. 2 Typical Forward Characteristics

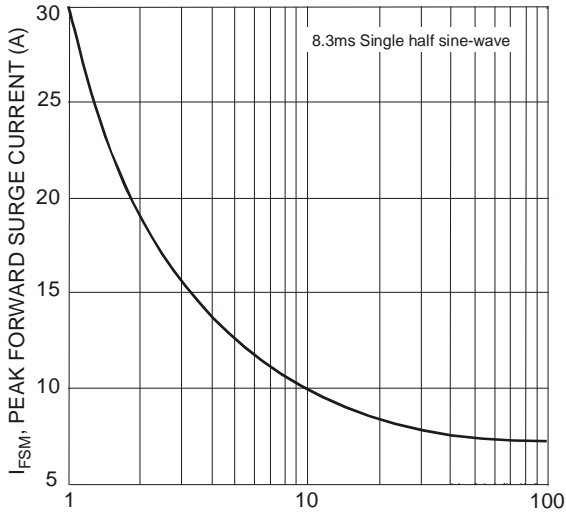


Fig. 3 Typical Forward Characteristics

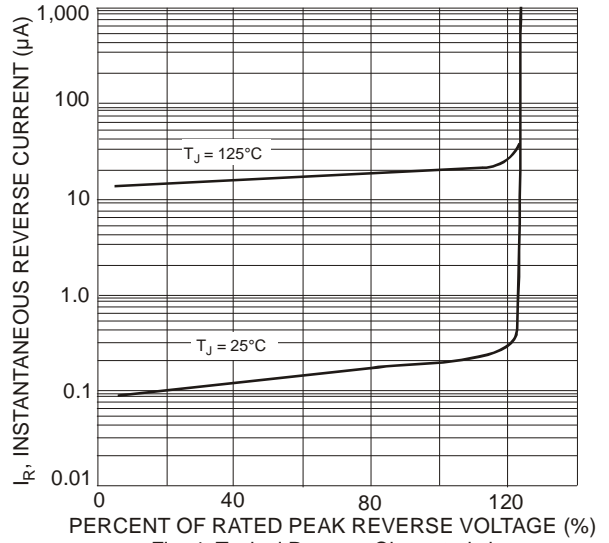
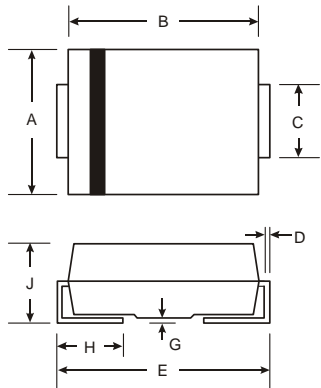


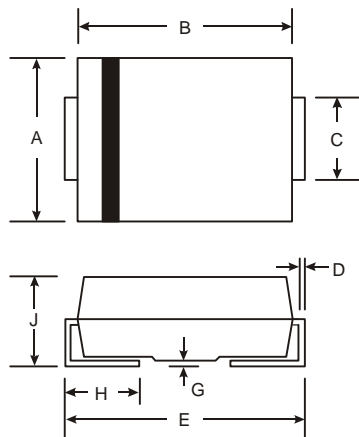
Fig. 4 Typical Reverse Characteristics

Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



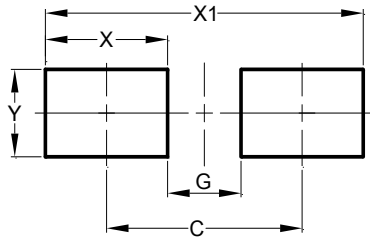
SMA		
Dim	Min	Max
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.05	0.20
H	0.76	1.52
J	1.96	2.40
All Dimensions in mm		



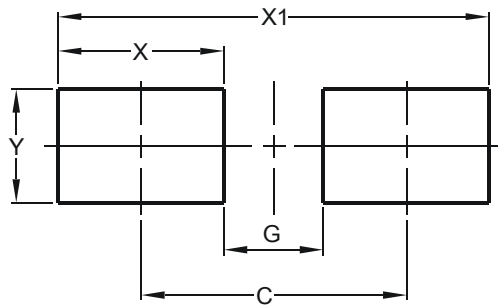
SMB		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.57
C	1.96	2.21
D	0.15	0.31
E	5.00	5.59
G	0.05	0.20
H	0.76	1.52
J	2.00	2.50
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



SMA	
Dimensions	Value (in mm)
C	4.00
G	1.50
X	2.50
X1	6.50
Y	1.70



SMB	
Dimensions	Value (in mm)
C	4.30
G	1.80
X	2.50
X1	6.80
Y	2.30

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